

4/2004 SN 10/078,766

FIAS: [Default FAS] Workspace [Flat Panel LANDSCAPE] [back up wsp.1]

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Drafts

ISNR:

BRS:

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Active

- L1: (14912) (205/50-333). CCLS.
- L2: (388674) copper or Cu
- L3: (95555) citric
- L4: (384614) pH
- L5: (405) 11 and 12 and 13 and 14
- L6: (2980) 12 same 13
- L7: (102) 11 and 16 and 14
- L8: (698) 12 same 13 same 14
- L9: (51) 11 and 18
- L10: (51) 17 not 19
- L11: (44376) electroplating or electrodeposits
- L12: (7461) electrolysis near2 deposits
- L13: (3675) electrochems near2 deposits
- L14: (50446) 111 or 112 or 113
- L15: (154314) wafer or wafers
- L16: (394489) semiconductor or semiconductors
- L17: (432467) 115 or 116
- L18: (85) 18 and 114 and 117
- L19: (62) 118 not 17
- L20: (15761) complexing adj (agent or agents)
- L21: (734) 12 same 14 same 120
- L22: (126) 11 and 121
- L23: (99) 122 not 17

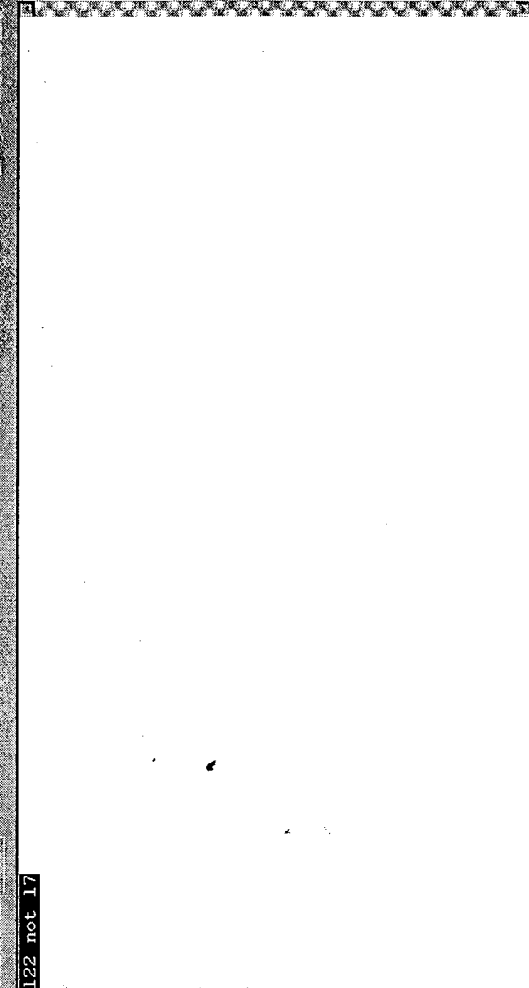
Failed

Search Lst Browse Delete Clear

DB: USPAT-USPUB

Default operator: OR

122 not 17



BRS Item SRS Item Images Text HTML

Document ID Issue Date Pages Title

Current OR Current XRef Retrieval C Inventor

U S C P L I Z R PT

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FILE EAST - [Untitled1:1]

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- L1: (14912) (205/50-333). CCLs.
- L2: (396130) copper or Cu or cuprous or cupric
- L3: (28676) complexing
- L4: (2) aminealkanol or aminealkanols
- L5: (42149) diethanolamine or monoethanolamine
- L6: (59568) diethanolamine or triethanolamine
- L7: (80745) 14 or 15 or 16
- L8: (544) 13 same 17
- L9: (26) 18 and 11 and 12

Search List Browse Queue Data
 Data USPAT:US-PGPUB Default operator: OH

18 and 11 and 12

	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval C	Inventor	U	S	C	P	1	2	3	PT.
1	US 20030155247 A1	20030821	8	Process for electroplating silicon wafers	205/157			Miura, Takeshi et al.	✓	□	□	□	□	□	□	□
2	US 6565731 B1	20030520	11	Electroplating process	205/125	205/159; 205/164		Coumble, Edward C. et al.	□	✓	□	□	□	□	□	□
3	US 6544398 B2	20030408	7	Non-cyanide-type gold-tin alloy plating bath	205/247	106/1.126; 205/252;		Uchida, Ei et al.	✓	□	□	□	□	□	□	□
4	US 6231619 B1	20010515	11	Electroplating process	205/126	205/125; 205/206		Florio, Steven M. et al.	✓	□	□	□	□	□	□	□
5	US 6176996 B1	20010123	4	Tin alloy plating compositions	205/254	106/1.125; 205/253		Moon, Sungsoo	✓	□	□	□	□	□	□	□
6	US 6106689 A	20000822	29	Process for forming zinc oxide film and processes for	205/333	205/164; 205/167;		Matsuyama, Jinsho	✓	□	□	□	□	□	□	□
7	US 5908543 A	19990601	9	Method of electroplating non-conductive materials	205/159	106/1.105; 106/1.11;		Matsunami, Takashi et al.	✓	□	□	□	□	□	□	□
8	US 5858198 A	19990112	10	Electroplating process	205/183	205/122; 205/125;		Florio, Steven M. et al.	✓	□	□	□	□	□	□	□
9	US 5770032 A	19980623	7	Metallizing process	205/210	205/125; 205/126;		Cane, Frank N.	✓	□	□	□	□	□	□	□
10	US 5738776 A	19980414	9	Electroplating process	205/118	205/125; 205/166;		Florio, Steven M. et al.	✓	□	□	□	□	□	□	□
11	US 5725640 A	19980310	10	Composition and process for treating a surface coated	106/1.105	106/1.11; 205/210;		Joshi, Nayan E. et al.	✓	□	□	□	□	□	□	□
12	US 5683565 A	19971104	7	Electroplating process	205/109	205/118; 205/125;		Florio, Steven M. et al.	✓	□	□	□	□	□	□	□